10/042,408

L Numbe	r Hits		DB	Time stamp
3	003	((((ball adj grid) BGA PGA (pin adj grid))	USPAT;	2004/10/29 12:52
		and @ad<19940318) and wire) and (encapsula\$5	US-PGPUB;	2002, 20, 20
		epoxy resin packag\$3)	EPO; JPO;	
		cpony resum packages,	DERWENT;	
			IBM TDB	
6	81	(((((ball adj grid) BGA PGA (pin adj grid))	USPAT;	2004/10/29 12:47
	01	and @ad<19940318) and wire) and (encapsula\$5	US-PGPUB;	2001, 20, 25 == 11.
		epoxy resin packag\$3)) and wafer	EPO; JPO;	
		epony rebrin publicages, y and ware-	DERWENT;	
			IBM TDB	
7	140	((ball adj grid) BGA PGA (pin adj grid)) and	USPAT;	2004/10/29 13:13
		@ad<19940318 and wafer	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		1	IBM TDB	
8	103	(substrate near8 pattern\$3) and @ad<19940318	USPAT;	2004/10/29 13:15
		and (BGA PGA)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
9	146	((metal\$8 wir\$3) near8 pattern\$3) and	USPAT;	2004/10/29 13:23
		@ad<19940318 and (BGA PGA)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	0	((metal\$8 wir\$3) near8 (repeat\$4 adj	USPAT;	2004/10/29 13:24
		pattern\$3)) and @ad<19940318 and (BGA PGA)	US-PGPUB;	
		·	EPO; JPO; DERWENT;	
			IBM TDB	
11	100	((metal\$8 wir\$3) near8 (repeat\$4 adj	USPAT;	2004/10/29 13:25
	100	pattern\$3)) and @ad<19940318	US-PGPUB;	2004/10/25 13.25
		paccernos// and waddission	EPO; JPO;	
			DERWENT;	
	İ		IBM TDB	
12	34	(((metal\$8 wir\$3) near8 (repeat\$4 adj	USPAT;	2004/10/29 14:05
	\	pattern\$3)) and @ad<19940318) and substrate	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	4	(("5729894") or ("5578869")).PN.	USPAT;	2004/10/29 14:06
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	3000	//hall add amid) DON DON /-in add amid))	IBM_TDB	2004/10/29 10:55
_	3828	((ball adj grid) BGA PGA (pin adj grid)) and @ad<19940318	USPAT; US-PGPUB;	2004/10/23 10:55
	1	WAUKI774U310	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	844	(((ball adj grid) BGA PGA (pin adj grid))	USPAT;	2004/10/29 10:55
	034	and @ad<19940318) and wire	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	669	((((ball adj grid) BGA PGA (pin adj grid))	USPAT;	2004/10/29 12:46
		and @ad<19940318) and wire) and (encapsula\$5	US-PGPUB;	
		epoxy resin packag\$3)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	